Heraeus

Electronics

New Product: Microbond® DA5118 P

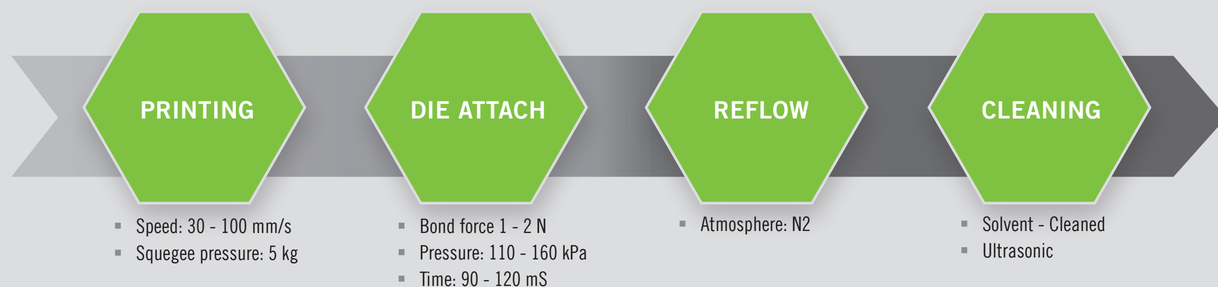
Solvent Clean High-Lead Printing Solder Paste

Microbond® DA5118 P is a high melting point solder paste for printing in die, clip and bridge applications. The paste exhibits stable rheology, excellent paste deposit, low void rates and easy cleanability to deliver a high-reliability joint. DA5118 P ease of handling offers the highest UPH for high volume production of leadframe devices. Spacer options guarantee bond-line control to meet increasing reliability requirements and address thinner dies packaging.

Microbond® DA5118 P Benefits

- Halogen zero
- Exceptional printing consistency
- Suitable for small to large dies
- Spacer option for bondline standoff
- Long work life
- Wide reflow temperature window
- Low void rates
- Excellent cleanability
- Enables higher throughput

DA5118 P Solder Paste Process and Application



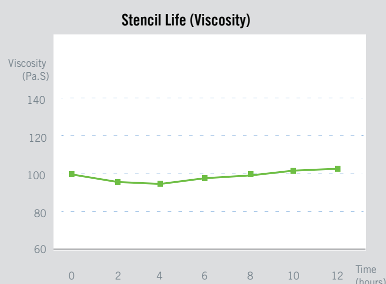
Printing
- Speed: 30 - 100 mm/s
- Squegee pressure: 5 kg

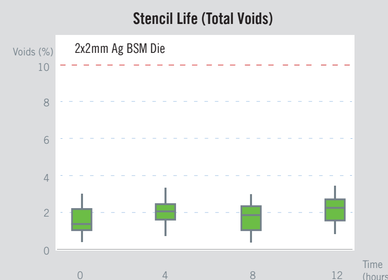
Die Attach
- Bond force 1 - 2 N
- Pressure: 110 - 160 kPa
- Time: 90 - 120 mS

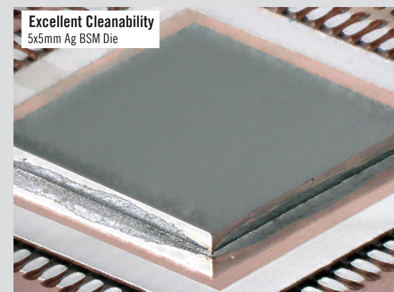
Reflow
- Atmosphere: N2

Cleaning
- Solvent - Cleaned
- Ultrasonic

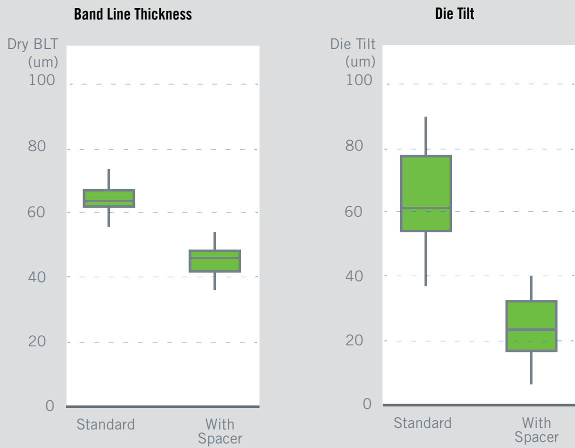
Continuous Printing Performance







DA5118 P Spacer Option

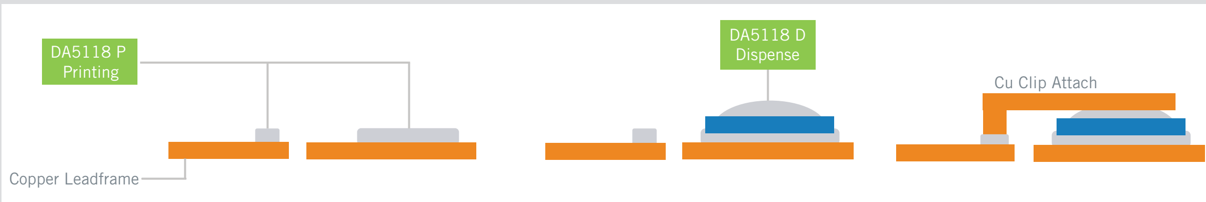


Process Recommendation for Power Clip Attachment

Product Properties Table

Physical Properties	DA5118 P
Alloy	PbSn5Ag2.5
	PbSn5Ag2.5 + Spacers
	PbSn5
Metal Content	91 %
Halogen Content	Halogen zero
Flux Activity	ROL0
Application/Process	
Printing Speed	up to 150 mm/s
Reflow Temperature	360 - 390°C
Reflow Atmosphere	N2
Features & Benefits	
Cleaning	Solvent Clean
Work Life	≥ 12 hr
Shelf Life	4 mths
Storage Condition	2 - 10 °C

Process Recommendation for Power Clip Attachment



The data given here is valid. We reserve the right to make technical alterations.

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The descriptions and engineering data shown here have been compiled by Heraeus using commonly-accepted procedures, in conjunction with modern testing equipment, and have been compiled as according to the latest factual knowledge in our possession. The information was up-to date on the date this document was printed (latest versions can always be supplied upon request). Although the data is considered accurate, we cannot guarantee accuracy, the results obtained from its use, or any patent infringement resulting from its use (unless this is contractually and explicitly agreed in writing, in advance). The data is supplied on the condition that the user shall conduct tests to determine materials suitability for particular application.

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